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F	EC17156	4/8/22	SM	LT/DF

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 <small>a MICROCHIP company</small> MOUNT HOLLY SPRINGS, PA 17065	Oscillator Specification, Hybrid VCXO For Hi-Rel Standard, LVPECL Output			
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THE RECORD OF APPROVAL FOR THIS DOCUMENT IS MAINTAINED ELECTRONICALLY WITHIN THE ERP SYSTEM	CODE IDENT NO	SIZE	DWG. NO.	REV
	00136	A	DOC204898	F
UNSPECIFIED TOLERANCES: N/A			SHEET 1 OF 19	

1. SCOPE

1.1 General. This specification defines the design, assembly and functional evaluation of high reliability, hybrid voltage controlled oscillators produced by Vectron. Devices delivered to this specification represent the standardized Parts, Materials and Processes (PMP) Program developed, implemented and certified for advanced applications and extended environments.

1.2 Applications Overview. The designs represented by these products were primarily developed for the MIL-Aerospace community. The lesser Design Pedigrees and Screening Options imbedded within DOC204898 bridge the gap between Space and COTS hardware by providing custom hardware with measures of mechanical, assembly and reliability assurance needed for Military or Ruggedized COTS environments.

2. APPLICABLE DOCUMENTS

2.1 Specifications and Standards. The following specifications and standards form a part of this document to the extent specified herein. The issue currently in effect on the date of quotation will be the product baseline, unless otherwise specified. In the event of conflict between the texts of any references cited herein, the text of this document shall take precedence.

Military

MIL-PRF-55310 Oscillators, Crystal Controlled, General Specification For
MIL-PRF-38534 Hybrid Microcircuits, General Specification For

Standards

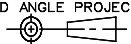
MIL-STD-202 Test Method Standard, Electronic and Electrical Component Parts
MIL-STD-750 Test Method Standard, Test Methods for Semiconductor Devices
MIL-STD-883 Test Methods and Procedures for Microelectronics

Other


DOC204944 Test Specification, Hybrid VCXO, Hi-Rel Standard, LVPECL Output
QSP-90100 Quality Systems Manual, Vectron
VL-65339 Identification Common Documents, Materials and Processes, Hi-Rel
XO
DOC203982 DPA Specification
QSP-91502 Procedure for Electrostatic Discharge Precautions
DOC208191 Enhanced Element Evaluation for Space Level Hybrid Oscillators

3. GENERAL REQUIREMENTS

3.1 Classification. All devices delivered to this specification are of hybrid technology conforming to Type 1, Class 2 of MIL-PRF-55310. Primarily developed as a Class S equivalent specification, options are imbedded within it to also produce Class B, Engineering Model and Ruggedized COTS devices. Devices carry a Class 2 ESDS classification per MIL-PRF-38534.

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- 3.2 Item Identification. Unique model number series are utilized to identify device package configurations as listed in Table 1.
- 3.3 Absolute Maximum Ratings.
- a. Supply Voltage Range (V_{CC}): 0Vdc to +6.0Vdc
 - b. Storage Temperature Range (T_{STG}): -65°C to +125°C
 - c. Junction Temperature (T_J): +150°C
 - d. Lead Temperature (soldering, 10 seconds): +300°C
 - e. Control Voltage Input (V_c) 0Vdc to +6.0Vdc
- 3.4 Design, Parts, Materials and Processes, Assembly, Inspection and Test.
- 3.4.1 Design. The ruggedized designs implemented for these devices are proven in military and space applications under extreme environments. Designs utilize 4-point crystal mounting in combination with Established Reliability (MIL-ER) components where possible. When specified, radiation tolerant active devices up to 100krad (Si) (RHA level R) is met by utilizing swept quartz and active device lots that have passed testing to that level.
- 3.4.1.1 Design and Configuration Stability. Barring changes to improve performance by reselecting passive chip component values to offset component tolerances, there will not be fundamental changes to the design or assembly or parts, materials and processes after first product delivery of that item without written approval from the procuring activity.
- 3.4.1.2 Environmental Integrity. Designs have passed the environmental qualification levels of MIL-PRF-55310. These designs have also passed extended dynamic levels of at least:
- a. Sine Vibration: MIL-STD-202, Method 204, Condition G (30g pk.)
 - b. Random Vibration: MIL-STD-202, Method 214, Condition II-J (43.92g rms, three minute duration in each of three mutually perpendicular directions)
 - c. Mechanical Shock: MIL-STD-202, Method 213, Condition F (1500g, 0.5ms)
- 3.4.2 Prohibited Parts, Materials and Processes. The items listed are prohibited for use in high reliability devices produced to this specification.
- a. Gold metallization of package elements without a barrier metal.
 - b. Zinc chromate as a finish.
 - c. Cadmium, zinc, or pure tin external or internal to the device.
 - d. Plastic encapsulated semiconductor devices.
 - e. Ultrasonically cleaned electronic parts.
 - f. Heterojunction Bipolar Transistor (HBT) technology.
 - g. ‘getter’ materials
- 3.4.3 Assembly. Manufacturing utilizes standardized procedures, processes and verification methods to produce MIL-PRF-55310 Class S / MIL-PRF-38534 Class K equivalent devices. MIL-PRF-38534 Group B Option 1 in-line inspection is included on radiation hardened part numbers to further verify lot pedigree. Devices are handled in accordance with Vectron document QSP-91502 (Procedure for Electrostatic Discharge Precautions). Element replacement will be as specified in MIL-PRF-38534, Rev L.

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- 3.4.4 Inspection. The inspection requirements of MIL-PRF-55310 apply to all devices delivered to this document. Inspection conditions and standards are documented in accordance with the Quality Assurance, ISO-9001 and AS9100 derived, System of QSP-90100.
- 3.4.5 Test. The Screening test matrix of Table 5 is tailored for selectable-combination testing to eliminate costs associated with the development/maintenance of device-specific documentation packages while maintaining performance integrity.
- 3.4.6 Marking. Device marking shall be in accordance with the requirements of MIL-PRF-55310. In addition, when devices are identified with laser marking, the Resistance to Solvents test specified in MIL-PRF-55310 Group C, Mil-PRF-55310 Qualification or MIL-PRF-38534 Group B Inspection will not be performed.
- 3.4.7 Ruggedized COTS Design Implementation. Design Pedigree “D” devices (see ¶ 5.2) use the same robust designs found in the other device pedigrees. They do not include the provisions of traceability or the Class-qualified components noted in paragraphs 3.4.3 and 4.1.

4. DETAIL REQUIREMENTS

4.1 Components

4.1.1 Crystals. Cultured quartz crystal resonators are used to provide the selected frequency for the devices. The optional use of Premium Q swept quartz can, because of its processing to remove impurities, be specified to minimize frequency drift when operating in radiation environments. In accordance with MIL-PRF-55310, the manufacturer has a documented crystal element evaluation program.

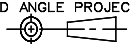
4.1.2 Passive Components.

4.1.2.1 For Design Pedigree E, where available, resistors shall be Established Reliability, Failure Rate R (as a minimum) and capacitors shall be Failure Rate S. Where resistors and capacitors are not available as ER parts, and for all other passive components, the parts shall be from homogeneous manufacturing lots that have successfully completed the Enhanced Element Evaluation of DOC208191 which meets the requirements of Mil-PRF-38534 Revision L for Class K.

4.1.2.2 For Design Pedigrees R, V and X, where available, resistors shall be Established Reliability, Failure Rate R (as a minimum) and capacitors shall be Failure Rate S. Where resistors and capacitors are not available as ER parts, and for all other passive components, the parts shall be from homogeneous manufacturing lots that have successfully completed the Class K Element Evaluation of Mil-PRF-38534 Revision K for Class K.

4.1.2.3 For Design Pedigrees B and C, all passive elements shall comply with the Element Evaluation requirements of Mil-PRF-55310 Class B as a minimum.

4.1.2.4 For Design Pedigree D, the passive elements will be COTs level or higher.

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4.1.2.5 When used, inductors will be open construction and may use up to 47-gauge wire.

4.1.3 Microcircuits.

4.1.3.1 For Design Pedigree E, the microcircuits shall be from homogeneous wafer lots that meet the Enhanced Element Evaluation requirements in DOC208191 and meet the requirements of Mil-PRF-38534 Revision L for Class K.

4.1.3.2 For Design Pedigree R, V and X, microcircuits shall be from homogeneous wafer lots that have successfully completed the MIL-PRF-38534, Revision K Lot Acceptance Tests for Class K.

4.1.3.3 For Design Pedigrees B and C, microcircuits are procured from wafer lots that have successfully completed the MIL-PRF-55310 Lot Acceptance Tests for Class B as a minimum.

4.1.3.4 For Design Pedigree D, microcircuits can be COTs level or higher.

4.1.4 Semiconductors.

4.1.4.1 For Design Pedigree E, the semiconductors shall be from homogeneous wafer lots that meet the Enhanced Element Evaluation requirements in DOC208191.


4.1.4.2 For Design Pedigree R, V and X semiconductors shall be from homogeneous wafer lots that have successfully completed the MIL-PRF-38534, Revision K Lot Acceptance Tests for Class K devices as a minimum.

4.1.4.3 For Design Pedigree B and C, semiconductors are procured from wafer lots that have successfully completed the MIL-PRF-55310 Lot Acceptance Tests for Class B devices as a minimum.

4.1.4.4 For Design Pedigree D, semiconductors can be COTs level or higher.

4.1.5 Radiation. When optionally specified, further testing is performed on the bipolar transistor for radiation hardness assurance up to 100krad (Si) total ionizing dose (TID) and for Enhanced Element Evaluation as specified in DOC208191. The LVPECL output buffer, identified by a unique part number, has undergone RLAT to 100krad (Si) ELDRS. Varactor diodes are considered insensitive to total ionizing dose effects.

4.1.6 Packages. Packages are procured that meet the construction, lead materials and finishes as specified in MIL-PRF-55310. All leads are Kovar with gold plating over a nickel underplate. Package lots are evaluated in accordance with the requirements of MIL-PRF-38534. Vectron will not perform Salt Spray testing as part of MIL-PRF-55310 Group C/Qualification. In

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accordance with MIL-PRF-55310, package evaluation results for salt atmosphere will be substituted for Salt Spray testing during MIL-PRF-55310 Group C/Qualification.

4.1.7 Traceability and Homogeneity. All design pedigrees except option D have active device lots that are traceable to the manufacturer's individual wafer; all other elements and passive components are traceable to their manufacturer and incoming inspection lots. Design pedigrees E, R, V and X have homogenous material. In addition, swept quartz crystals are traceable to the quartz bar and the processing details of the autoclave lot, as applicable. A production lot, as defined by Vectron, is all oscillators that have been kitted and assembled as a single group. After the initial kitting and assembly, this production lot may be divided into multiple sublots to facilitate alignment and test capacity.

4.2 Mechanical.

4.2.1 Package Outline. Table 1 links each Hi-Rel Standard Model Number of this specification to a corresponding package style. Mechanical Outline information of each package style is found in the referenced Figure.

4.2.2 Thermal Characteristics. The worst-case thermal characteristics of each package style and active device are found in Table 4.

4.2.3 Lead Forming. When lead forming option is specified, the applicable leak test specified in screening will be performed after forming.

4.3 Electrical.

4.3.1 Input Power. Devices are designed for standard +3.3 volt dc operation, $\pm 5\%$. Current is measured, no load, at maximum rated operating Voltage.

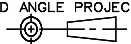
4.3.2 Temperature Range. Operating range is -40°C to $+85^{\circ}\text{C}$. Units may be operated from -55°C to $+125^{\circ}\text{C}$; however, electrical performance may be degraded.

4.3.3 Absolute Pull Range. Absolute pull range is defined as the minimum guaranteed amount the VCXO can be varied, about the center frequency (f_0). It accounts for degradations including temperature stability (-40 to 85°C), aging (15 years), radiation effects, power supply variations ($\pm 5\%$) and load variations ($\pm 10\%$).

4.3.4 Frequency Aging. When tested in accordance with MIL-O-55310 Group B inspection, the 15-year aging projection shall not cause the minimum APR limit to be exceeded.

4.3.5 Operating Characteristics. Symmetrical square wave limits are dependent on the device frequency and are in accordance with Table 2 and Figure 1. Start-up time is 10.0 msec. maximum.

4.3.6 Output Load. 50Ω to $V_{cc}-2.0\text{V}$ (each output)

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5. QUALITY ASSURANCE PROVISIONS AND VERIFICATION

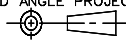
5.1 Verification and Test. Device lots shall be tested prior to delivery in accordance with the applicable Screening Option letter as stated by the 15th character of the part number. Table 5 tests are conducted in the order shown and annotated on the appropriate process travelers and data sheets of the governing test procedure. For devices that require Screening Options that include MIL-PRF-55310 Group A testing, the Post-Burn-In Electrical Test and the Group A Electrical Test are combined into one operation.

5.1.1 Screening Options. The Screening Options, by letter, are summarized as:

- A Modified MIL-PRF-38534 Class K
- B Modified MIL-PRF-55310 Class B Screening & Group A Quality Conformance Inspection (QCI)
- C Modified MIL-PRF-55310 (Rev E) Class S Screening & Group A QCI
- D Modified MIL-PRF-38534 Class K with Group B Aging
- E Modified MIL-PRF-55310 Class B Screening, Groups A & B QCI
- F Modified MIL-PRF-55310 (Rev E) Class S Screening, Groups A & B QCI
- G Modified MIL-PRF-55310 Class B Screening & Post Burn-in Nominal Electricals
- S MIL-PRF-55310 (Rev F) Class S Screening & Groups A & B QCI
- X Engineering Model (EM)

5.2 Optional Design, Test and Data Parameters. The following is a list of design, assembly, inspection and test options that can be selected or added by purchase order request.

- a. Design Pedigree (choose one as the 5th character in the part number):
 - (E) Enhanced Element Evaluation, (MIL-PRF-38534 Rev L for Class K components as specified in DOC208191) 100krad die, Premium Q Swept Quartz
 - (R) Hi-Rel design w/100krad Class K die, Premium Q Swept Quartz
 - (V) Hi-Rel design w/100krad Class K die, Non-Swept Quartz
 - (X) Hi-Rel design w/ Non-Swept Quartz, Class K die
 - (B) Hi-Rel design w/ Swept Quartz, Class B die
 - (C) Hi-Rel design w/ Non-Swept Quartz, Class B die
 - (D) Hi-Rel design w/ Non-Swept Quartz and commercial grade components
- b. Input Voltage, (B) for 3.3V as the 14th character
- c. Not Used
- d. Radiographic Inspection
- e. Group C Inspection: MIL-PRF-55310 Rev E (requires 8 destruct specimens)
- f. Group C Inspection: MIL-PRF-55310, Rev F (requires 8 destruct specimens, includes Random Vibration, MIL-STD-883, Method 1014 Leak Test and Life Test)
- g. Group C Inspection: MIL-PRF-38534, Table C-Xc, Condition PI [requires 8 destruct specimens – Life (5), RGA (3)]. Subgroup 1 fine leak test to be performed per MIL-STD-202, Method 112, Condition C.
- h. Internal Water-Vapor Content (RGA) samples and test performance
- i. MTBF Reliability Calculations
- j. Worst Case Analysis (unless otherwise specified, MIL-HDBK-1547)
- k. Derating and Thermal Analysis (unless otherwise specified, MIL-HDBK-1547 with $T_j \text{ Max} = +105^\circ\text{C}$; Derated Maximum Operating Temp = $T_j \text{ Max} - \Delta T_j$)

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- l. Process Identification Documentation (PID)
- m. Customer Source Inspection (pre-crystal mount pre-cap, post-crystal mount pre-cap and final). Due to components being mounted underneath the crystal blank, pre-crystal mount pre-cap inspection should be considered.
- n. Destruct Physical Analysis (DPA): MIL-STD-1580 with exceptions as specified in Vectron DOC203982.
- o. Qualification: In accordance with MIL-PRF-55310, Rev F Table IV (requires 16 destruct specimens).
- p. Qualification: In accordance with EEE-INST-002, Section C4, Table 3, Level 1 or 2 (requires 11 destruct specimens)
- q. High Resolution Digital Pre-Cap Photographs (20 Megapixels minimum)
- r. Hot solder dip of leads with Sn63/Pb37 solder prior to shipping
- s. As Designed Parts, Materials and Processes List

5.2.1 NASA EEE-INST-002. A combination of Design Pedigree R, Option S Screening, and Qualification per EEE-INST-002, Section C4, Table 3, meet the requirements of Level 1 and Level 2 device reliability.

5.3 Test Conditions. Unless otherwise stated herein, inspections are performed in accordance with those specified in MIL-PRF-55310. Process travelers identify the applicable methods, conditions and procedures to be used. Examples of electrical test procedures that correspond to MIL-PRF-55310 requirements are shown in Table 3.

5.4 Deliverable Data. The manufacturer supplies the following data, as a minimum, with each lot of devices (except devices with Screening Option X):

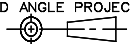
- a. Completed assembly and screening lot travelers, and screening data, including radiographic images, rework history and Certificate of Conformance.
- b. Electrical test variables data, identified by unique serial number.
- c. Special items when required by purchase order such as Frequency-Temperature Slew plots, Group C data and RGA data.
- d. Traceability, component LAT, enclosure LAT and RLAT (if specifically requested on the purchase order).

5.5 Discrepant Material. All MRB authority resides with the procuring activity.

5.6 Failure Analysis. Any failure during Qualification or Group C Inspection will be evaluated for root cause. The customer will be notified after occurrence and upon completion of the evaluation.

6. PREPARATION FOR DELIVERY

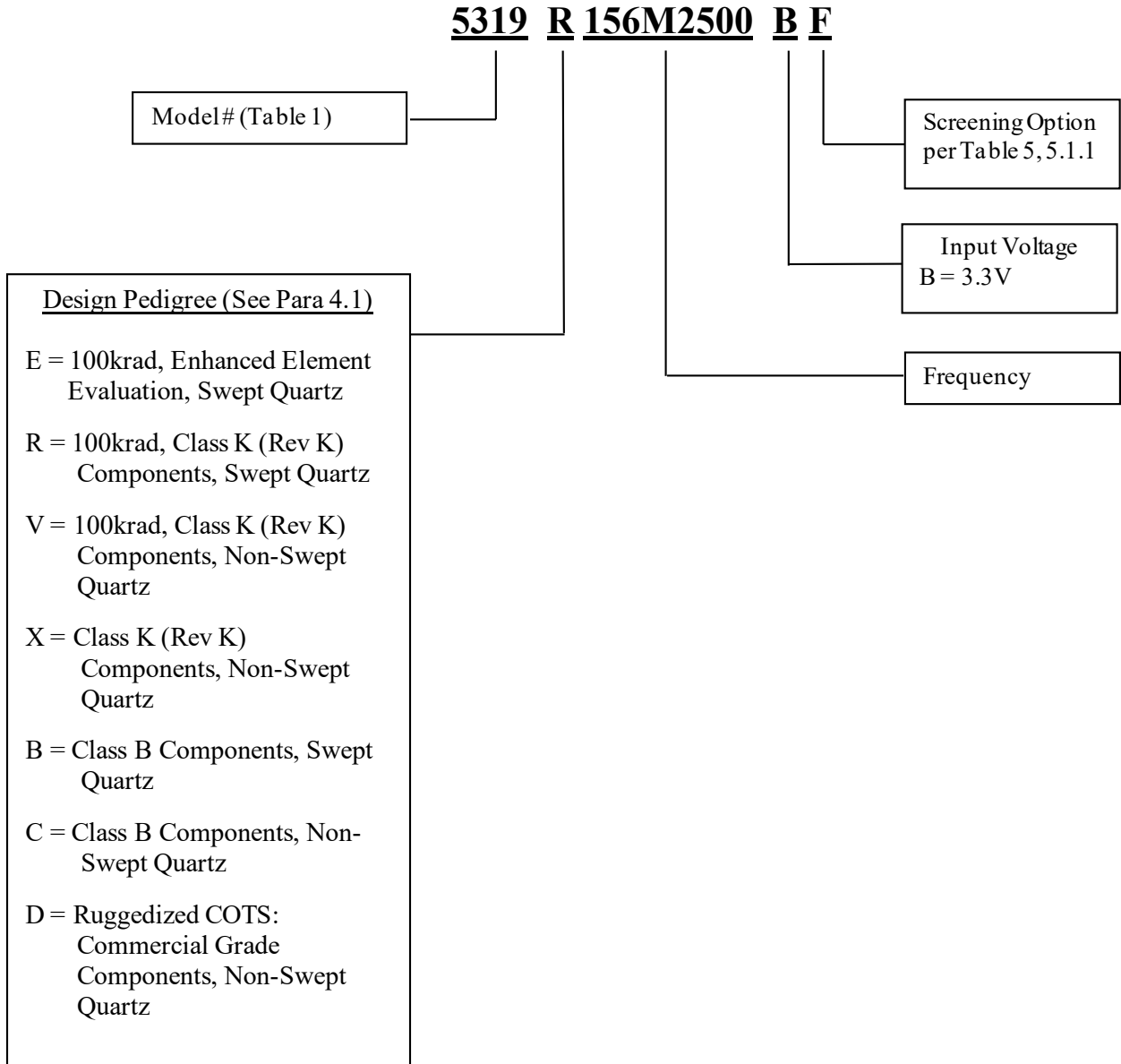
6.1 Packaging. Devices will be packaged in a manner that prevents handling and transit damage during shipping. Devices will be handled in accordance with MIL-STD-1686 for Class 1 devices.

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7. ORDERING INFORMATION

7.1 Ordering Part Number. The ordering part number is made up of an alphanumeric series of 15 characters. Design-affected product options, identified by the parenthetic letter on the Optional Parameters list (¶ 5.2a and b), are included within the device part number.

The Part Number breakdown is described as:



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- 7.1.1 Model Number. The device model number is the four (4) digit number assigned to a corresponding package and output combination per Table 1.
- 7.1.2 Design Pedigree. Class S variants correspond to either letter “E”, “R”, “V” or “X” and are described in paragraph 5.2a. Class B variants correspond to either letter “B” or “C” and are described in paragraph 5.2a. Ruggedized COTS, using commercial grade components, corresponds to letter “D”.
- 7.1.3 Output Frequency. The nominal output frequency is expressed in the format as specified in MIL-PRF-55310 utilizing eight (8) characters.
- 7.1.4 Input Voltage. Voltage is the 14th character, letter “B” represents +3.3V.
- 7.1.5 Screening Options. The 15th character is the Screening Option (letter A thru G, S or X) selected from Table 5.
- 7.2 Optional Design, Test and Data Parameters. Optional test and documentation requirements shall be specified by separate purchase order line items (as listed in ¶ 5.2c thru s).

HI-REL STANDARD MODEL #	PACKAGE	PIN I/O <u>1/</u>					MECHANICAL OUTLINE <u>2/</u>
		Vcc	Vc	Q	Qnot	Gnd/Case	
5319	16 Lead Flatpack	16	1	9	10	8, 11	FIGURE 2 or 4
5321 <u>3/</u>	16 Lead Flatpack	16	1	9	10	8, 11	FIGURE 3 or 5

1/. All unassigned pins have no internal connections or ties.

2/. Center frequencies greater than 320 MHz use mechanical outlines Figure 4 or 5.

3/. Model 5321 is a lead formed version of Model 5319. See Appendix A for recommended land pattern.

TABLE 1 - Item Identification and Package Outline


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Frequency Range: 25 MHz to 700 MHz 1/				
Temperature Range: -40°C to +85°C				
Absolute Pull Range: ±20 ppm min.				
Control Voltage (Vc) Range: 0.0V to +3.3V				
Slope: Positive				
Linearity: ±10% max.				
F vs. V Gain: 55 ppm/V typical				
Sub-Harmonics: -30 dBc max.				
Frequency-Voltage Tolerance: ±4 ppm max. (Vcc ±5%)				
Frequency Aging: 15 year projection based on 30 day test included in APR calculation				
Start-up Time: 10.0 ms max.				
Output Voltage: V _{OH} = Vcc-1.085 to Vcc-0.880, V _{OL} =Vcc-1.830 to Vcc-1.555				
Frequency Range (MHz)	Current, No load (mA max)	Rise / Fall Time (ps max.)	Duty Cycle (%)	BW Jitter, 12kHz-20MHz (ps rms max)
25 - <50	65	900	40 to 60	5.00
50 - <100	65	900	40 to 60	2.50
100 - 200	65	900	40 to 60	0.75
>200 - 320	65	600	40 to 60	0.5
>320 - 700	75	400	40 to 60	0.5

1/. Waveform measurement points and logic limits are in accordance with Figure 1.

TABLE 2 - Electrical Performance Characteristics

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PERATION LISTING	REQUIREMENTS AND CONDITIONS 1/
@ all Electrical tests	
Input Current (no load)	MIL-PRF-55310, Para 4.8.5.1
Initial Accuracy @ Ref. Temp.	MIL-PRF-55310, Para 4.8.6
Output Logic Voltage Levels	MIL-PRF-55310, Para 4.8.21.3
Rise and Fall Times	MIL-PRF-55310, Para 4.8.22
Duty Cycle	MIL-PRF-55310, Para 4.8.23
Frequency Deviation	MIL-PRF-55310, Para 4.8.31.1
Linearity	MIL-PRF-55310, Para 4.8.31.5 Nominal conditions only
Jitter	BW Jitter, 12kHz-20MHz Nominal conditions only
@ Post Burn-In Electrical only	
Overvoltage Survivability	MIL-PRF-55310, Para 4.8.4
Initial Freq. – Temp. Accuracy	MIL-PRF-55310, Para 4.8.10.1
Freq. – Voltage Tolerance	MIL-PRF-55310, Para 4.8.14
Start-up Time (fast/slow start)	MIL-PRF-55310, Para 4.8.29


1/. Waveform measurement points and logic limits are in accordance with Figure 1.

TABLE 3 - Electrical Test Parameters

Model #	Thermal Resistance Junction to Case θ_{jc} ($^{\circ}\text{C} / \text{W}$)	Δ Junction Temp. T_j ($^{\circ}\text{C}$ @ max. power)	Weight (Grams)
5319/5321	24.57	6.38	7.5

Note. These oscillators contain multiple active devices. This calculation shows the worst case θ_{jc} and temperature rise of those devices.

TABLE 4 - Typical Thermal Characteristics and Weight

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OPN. NO.	OPERATION LISTING	REQUIREMENTS AND CONDITIONS	Option A	Option B	Option C	Option D	Option E	Option F	Option G	Option S	Option X
	SCREENING	MIL Class Similarity (MIL-PRF-55310, Class S/B or MIL-PRF-38534, Class K)	K	B-	S-	K+	B	S (Rev E)		S (Rev F)	EM
			100%	100%	100%	100%	100%	100%	100%	100%	100%
1	Non-Destruct Bond Pull	MIL-STD-883, Meth 2023	X	NR	X	X	NR	X	NR	X	NR
2	Internal Visual	MIL-STD-883, Meth 2017 Class K, Meth 2032 Class K	X	X	X	X	X	X	X	X	X
3	Stabilization (Vacuum) Bake	MIL-STD-883, Meth 1008, Cond C, 150°C	X 48 hrs.	X 24 hrs.	X 48 hrs.	X 48 hrs.	X 24 hrs.	X 48 hrs.	X 24 hrs.	X 48 hrs.	X 24 hrs.
4	Random Vibration	MIL-STD-883, Meth 2026, Cond I-B, 15 mins in each axis	NR	NR	NR	NR	NR	NR	NR	X	NR
5	Thermal Shock	MIL-STD-883, Meth 1011, Cond A	NR	NR	X	NR	NR	X	NR	X	NR
6	Temperature Cycle	MIL-STD-883, Meth 1010, Cond. B (except Option S), 10 cycles min.	X	X	X	X	X	X	X	X Cond. C	NR
7	Constant Acceleration	MIL-STD-883, Meth 2001, Cond A, Y1 plane only, 5000 g's	X	X	X	X	X	X	X	X	NR
8	Particle Impact Noise Detection	MIL-STD-883, Meth 2020, Cond B (except Option S)	X	X	X	X	X	X	NR	X Cond. A	X
9	Electrical Testing, Pre Burn-In	Perform tests in Table 3. Nominal Vcc, nominal temperature	X	X	X	X	X	X	X	X	X
10	1 st Burn-In	MIL-STD-883, Meth 1015, Condition B	X 160 hrs.	X 160 hrs.	X 240 hrs.	X 160 hrs.	X 160 hrs.	X 240 hrs.	X 160 hrs.	X 240 hrs.	NR
11	Electrical Testing, Intermediate	Perform tests in Table 3. Nominal Vcc, nominal temperature	X	NR	NR	X	NR	NR	NR	NR	NR
12	2 nd Burn-In	MIL-STD-883, Meth 1015, Condition B	X 160 hrs.	NR	NR	X 160 hrs.	NR	NR	NR	NR	NR
13	Electrical Testing, Post Burn-In (Group A)	Perform tests in Table 3. Nominal Vcc & extremes, nominal temperature & extremes	X	X	X	X	X	X	X nom. Vcc	X	NR
14	Seal: Fine Leak Seal: Gross Leak	MIL-STD-202, Meth 112, Cond C (5 x 10 ⁻⁸ atm cc/sec max) MIL-STD-202, Meth 112, Cond D	X	X	X	X	X	X	X	NR	X
15	Seal: Fine Leak Seal: Gross Leak	MIL-STD-883, Meth 1014, Cond A2 or B1 MIL-STD-883, Meth 1014, Cond B2 or B3	NR	NR	NR	NR	NR	NR	NR	X	NR
16	Radiographic Inspection	MIL-STD-883, Meth 2012	X	AR	AR	X	AR	X	NR	X	NR
17	Solderability	MIL-STD-883, Meth 2003	<u>1/</u>	<u>1/</u>	<u>1/</u>	<u>1/</u>	<u>1/</u>	<u>1/</u>	<u>1/</u>	<u>1/</u>	NR
18	External Visual & Mechanical	MIL-STD-883, Meth 2009	X <u>2/</u>	X <u>2/</u>	X <u>2/</u>	X <u>2/</u>	X <u>2/</u>	X <u>2/</u>	X <u>2/</u>	X <u>2/</u>	X <u>2/</u>
19	Aging, 30 Day <u>3/</u> (M55310 Group B)	MIL-PRF-55310, para. 4.8.35.1	NR	NR	NR	X	13 pcs.	X	NR	X	NR
20	Group C Inspection (optional)	See Para 5.2 herein for details of supplier recommended Group C Inspection options	5.2(g)	5.2(e)	5.2(e)	5.2(g)	5.2(e)	5.2(e)	5.2(e)	5.2(f)	NR

LEGEND: X = Required, NR = Not Required, AR = As Required

TABLE 5 - Test Matrix

1/ Performed at package LAT. Include LAT data sheet

2/ When specified, RGA samples will be removed from the lot after completion of this operation. Use of Screening failures require customer concurrence.

3/ By customer request, the Aging test may be terminated after 15 days if the measured aging rate is less than one-half the specified aging rate, as described in paragraph 4.3.4.1 herein. Must be explicitly stated on the customer PO.

SIZE A	CODE IDENT NO. 00136	THIRD ANGLE PROJECTION 	UNSPECIFIED TOLERANCES N/A	DWG NO. DOC204898	REV. F	SHEET 13
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MICROCHIP CONFIDENTIAL

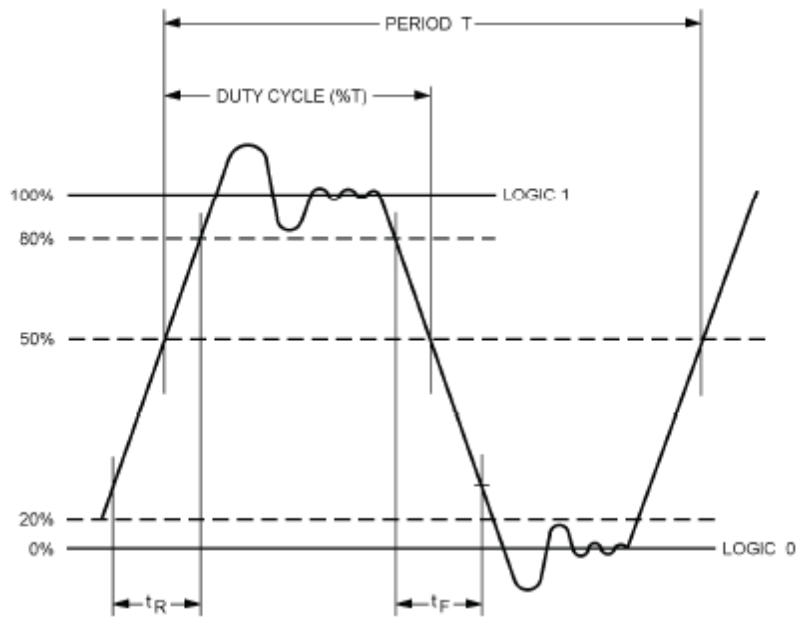
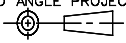


FIGURE 1
Differential Output Waveform

SIZE A	CODE IDENT NO. 00136	THIRD ANGLE PROJECTION 	UNSPECIFIED TOLERANCES N/A	DWG NO. DOC204898	REV. F	SHEET 14
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MICROCHIP CONFIDENTIAL

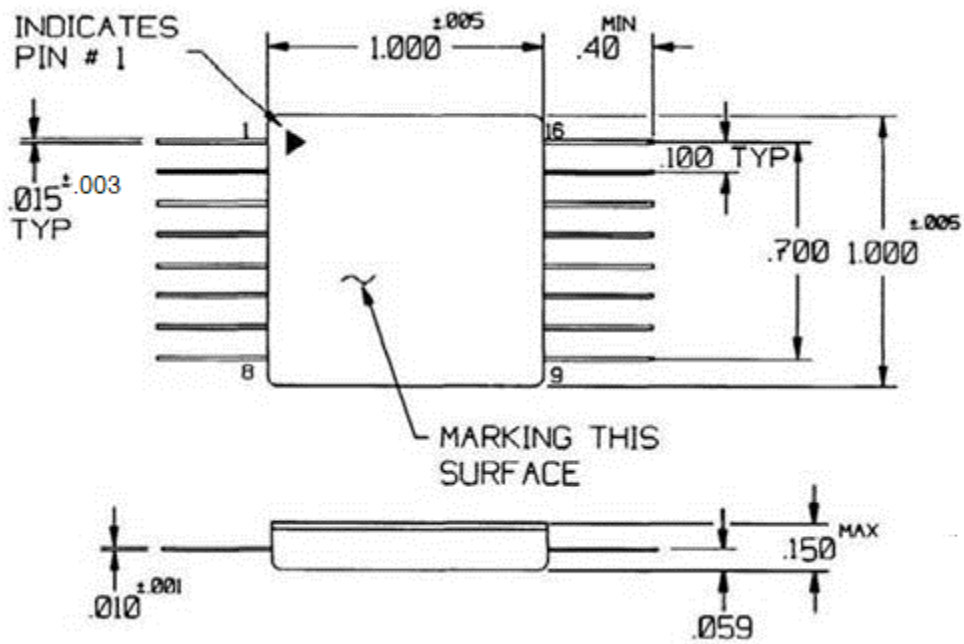
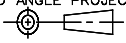


FIGURE 2
Model 5319 Package Outline

SIZE	CODE IDENT NO.	THIRD ANGLE PROJECTION	UNSPECIFIED TOLERANCES	DWG NO.	REV.	SHEET
A	00136		N/A	DOC204898	F	15

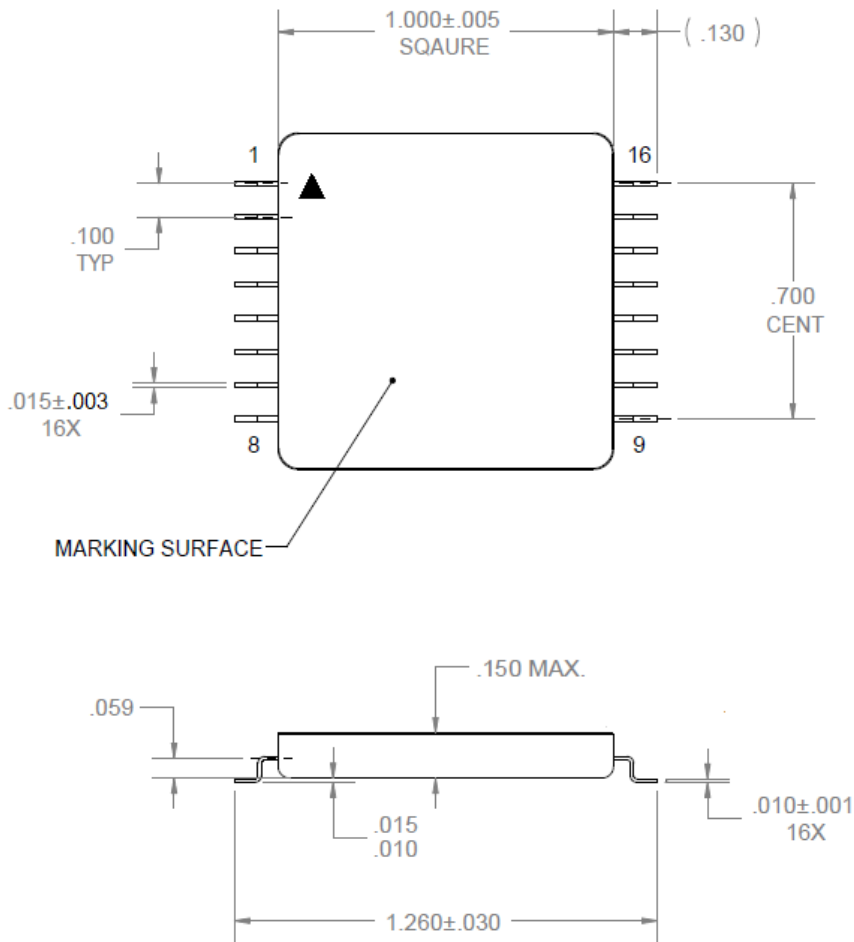
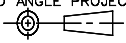


FIGURE 3
Model 5321 Package Outline

SIZE A	CODE IDENT NO. 00136	THIRD ANGLE PROJECTION 	UNSPECIFIED TOLERANCES N/A	DWG NO. DOC204898	REV. F	SHEET 16
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MICROCHIP CONFIDENTIAL

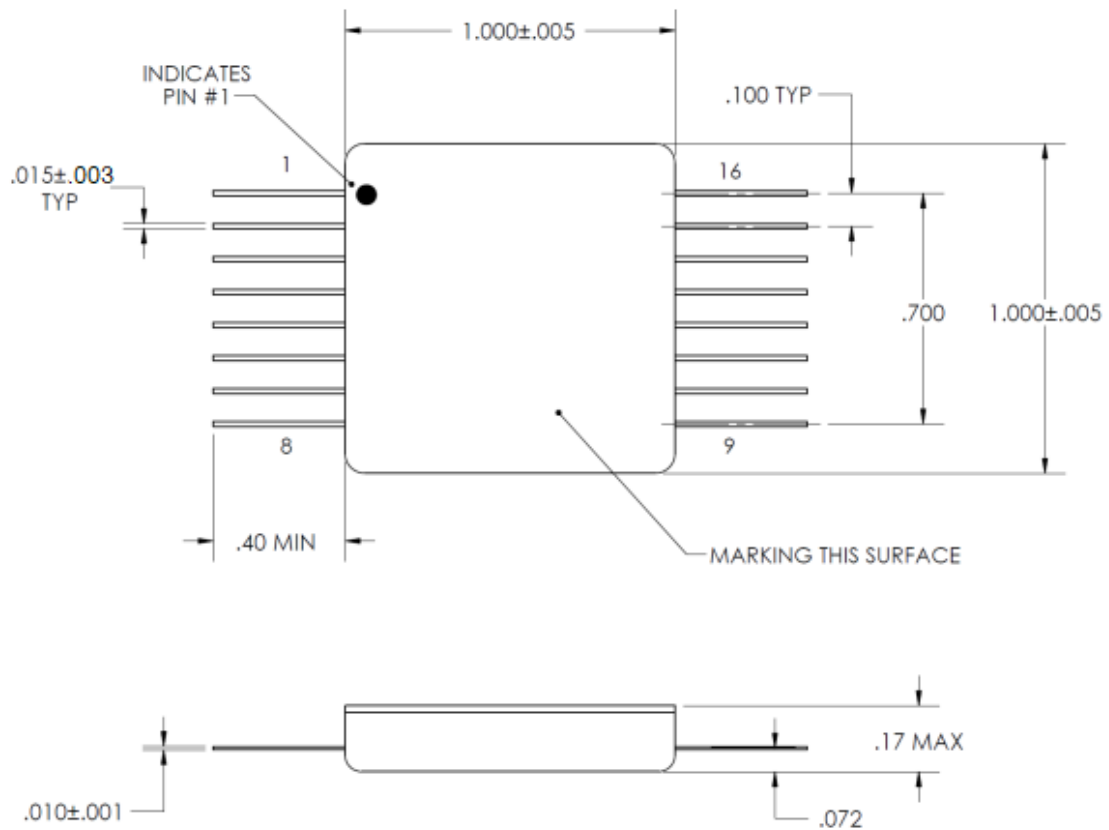
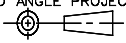


FIGURE 4
 Model 5319 Package Outline
 (Center Frequency >320 MHz)

SIZE A	CODE IDENT NO. 00136	THIRD ANGLE PROJECTION 	UNSPECIFIED TOLERANCES N/A	DWG NO. DOC204898	REV. F	SHEET 17
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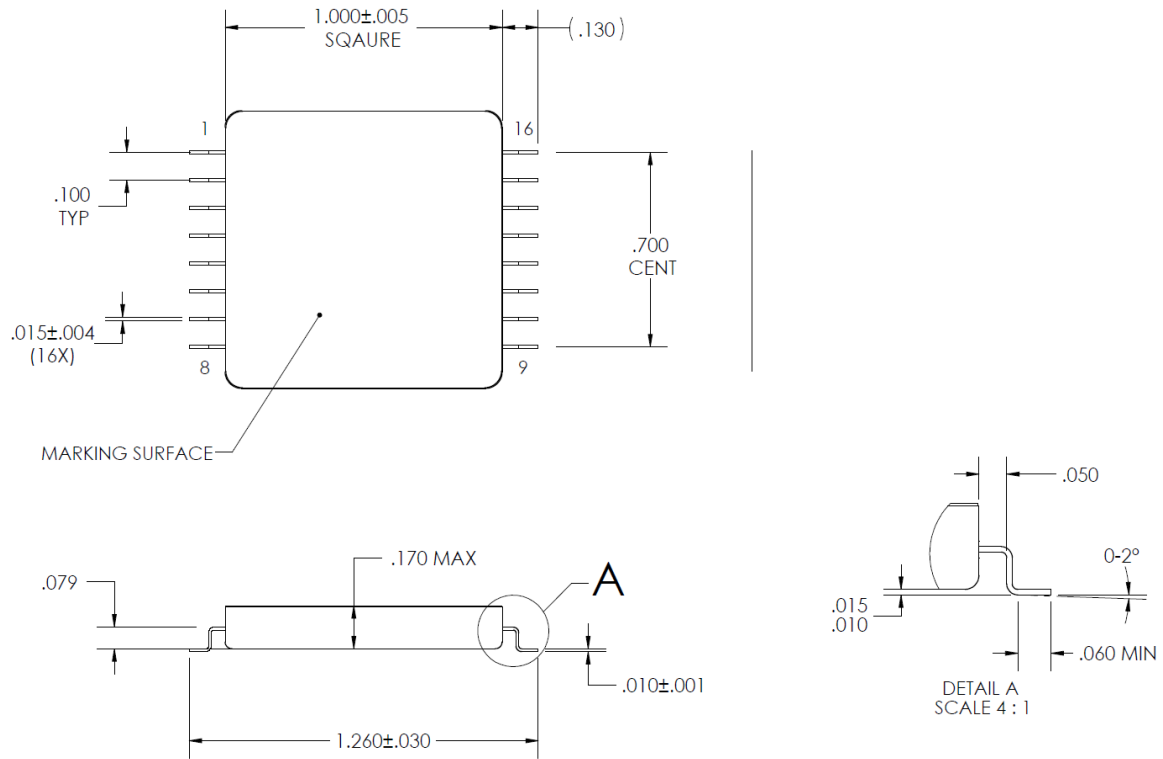
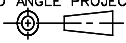
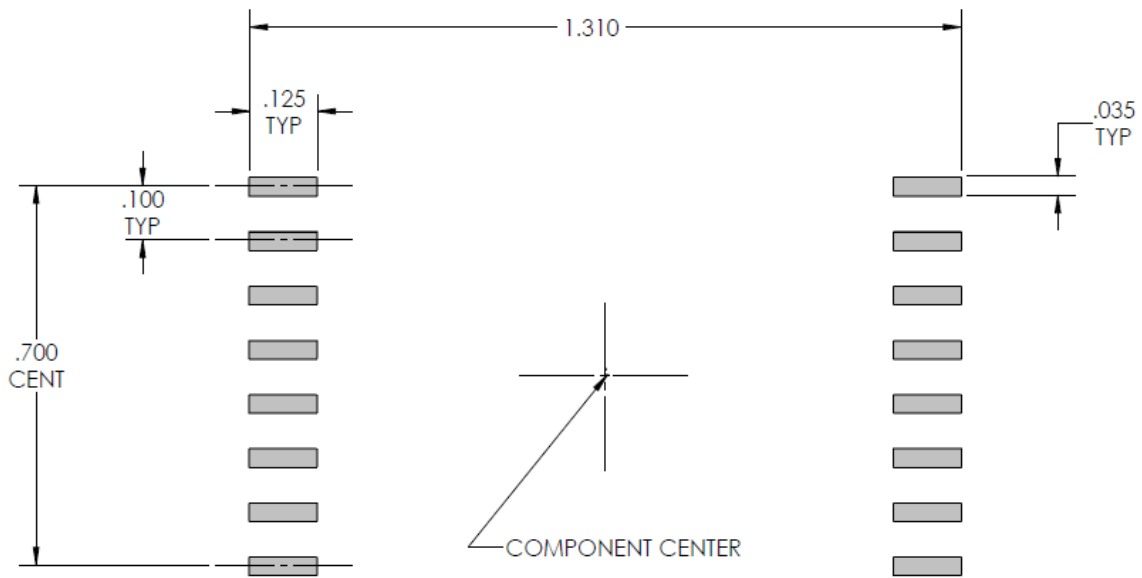


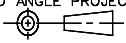
FIGURE 5
 Model 5321 Package Outline
 (Center Frequency >320 MHz)

SIZE	CODE IDENT NO.	THIRD ANGLE PROJECTION	UNSPECIFIED TOLERANCES	DWG NO.	REV.	SHEET
A	00136		N/A	DOC204898	F	18

APPENDIX A
Recommended Land Pattern



Model 5321

SIZE A	CODE IDENT NO. 00136	THIRD ANGLE PROJECTION 	UNSPECIFIED TOLERANCES N/A	DWG NO. DOC204898	REV. F	SHEET 19
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